

**AMENDMENTS TO THE CLAIMS**

1. (currently amended) ~~Method~~ A method for selectively metallizing a component which component comprises a first part-(1), constituted by a first material, and a second part-(2), constituted by a second material, the method comprising ~~next sequential~~ the steps of:

[[ -]] (a) applying a metallizing seed layer (6) ~~is applied~~ on at least a part of the surface of said first part and of said second part;

[[ - the]] (b) exposing a relevant surface of the component, including said metallizing seed layer, ~~is exposed~~ to a solvent (7) in which the material of said first part (1) is soluble and the material of said second part (2) is not soluble, thereby providing a metallizing seed layer on said second part but not on said first part.

2. (currently amended) ~~Method according to~~ The method of claim 1, ~~in which~~ wherein the first material and/or the second material is a plastic or polymer.

3. (currently amended) ~~Method according to~~ The method of claim 1, ~~in which~~ wherein the first material and/or the second material is a ceramic material.

4. (currently amended) ~~Method according to~~ The method of claim 1, ~~followed by a step wherein which further includes the step of exposing~~ the surface of the component ~~is exposed~~ to a metallizing environment-(9).

5. (currently amended) ~~System~~ A system for metallizing a component that comprises a first part-(1), constituted by a first material, and a second part-(2), constituted by a second material, the system comprising:

means for producing a metallizing seed layer (6) at the surface on at least a part of said first part and of said second part, and, ~~moreover,~~

means for exposing the relevant surface of the component, including said metallizing seed layer, ~~to be exposed~~ to a solvent (7) in which the material of said first part (1) is soluble and the material of said second part (2) is not.

6. (currently amended) ~~Component~~ A component comprising a first part-(1), constituted by a first material, and a second part-(2), constituted by a second material, ~~said second part of the component comprising a metallizing seed layer (8), the~~ which surface of said

first part ~~(1) being~~ is soluble and the surface of said second part ~~(2) being~~ is not soluble in at least one specific solvent, and

wherein the second part but not the first part comprises a metallizing seed layer.

7. (currently amended) ~~Component according to~~ The component of claim 6, in which the first material and/or the second material is a plastic or polymer material.

8. (currently amended) ~~Component according to~~ The component of claim 6, in which the first material and/or the second material is a ceramic material.

9. (currently amended) ~~Component according to~~ The component of claim 6, wherein said seed layer ~~(8)~~ of the second ~~component~~ part ~~(2) being~~ is covered by a metallic layer ~~(10)~~.

10. (new) The system of claim 5 which further includes:  
means for providing a metallizing environment.

11. (new) A component obtained by the method of claim 1.

12. (new) A component obtained by the method of claim 4.